MARKING DIAGRAMS



## **Quad 2-Input NOR Gate**

# **High-Performance Silicon-Gate CMOS**

## **MC74AC02, MC74ACT02**

#### **Features**

- Outputs Source/Sink 24 mA
- 'ACT02 Has TTL Compatible Inputs
- These are Pb-Free Devices

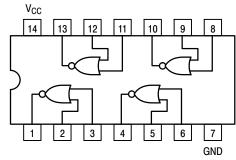
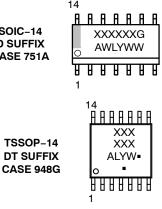


Figure 1. Pinout: 14-Lead Packages Conductors (Top View)





XXXXXX = Specific Device Code
A = Assembly Location
WL or L = Wafer Lot
Voor

Y = Year

WW or W = Work Week

G or • = Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

1

#### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Unit
V <sub>CC</sub>	DC Supply Voltage	- 0.5 to +6.5	V
VI	DC Input Voltage	$-0.5 \le V_{I} \le V_{CC} + 0.5$	V
Vo	DC Output Voltage (Note 1)	$-0.5 \le V_{O} \le V_{CC} + 0.5$	V
I <sub>IK</sub>	DC Input Diode Current	± 20	mA
I <sub>OK</sub>	DC Output Diode Current	± 50	mA
I <sub>O</sub>	DC Output Sink/Source Current	± 50	mA
I <sub>CC</sub>	DC Supply Current per Output Pin	± 50	mA
I <sub>GND</sub>	DC Ground Current per Output Pin	± 50	mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150	°C
TL	Lead temperature, 1 mm from Case for 10 Seconds	260	°C
TJ	Junction temperature under Bias	+ 150	°C
$\theta_{JA}$	Thermal Resistance (Note 2) SOIC TSSOP	116 150	°C/W
P <sub>D</sub>	Power Dissipation in Still Air at 25°C SOIC TSSOP	1077 833	mW
MSL	Moisture Sensitivity	Level 1	
F <sub>R</sub>	Flammability Rating Oxygen Index: 30% – 35%	UL 94 V-0 @ 0.125 in	
V <sub>ESD</sub>	ESD Withstand Voltage Human Body Model (Note 3) Charged Device Model (Note 4)	> 2000 > 1000	V
I <sub>Latch-Up</sub>	Latch-Up Performance Above V <sub>CC</sub> and Below GND at 85°C (Note 5)	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. IO absolute maximum rating must be observed.
- The package thermal impedance is calculated in accordance with JESD51–7.
   Tested to EIA/JESD22–A114–A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

#### RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter		Min	Тур	Max	Unit
V	Supply Voltage	'AC	2.0	5.0	6.0	V
V <sub>CC</sub>	Supply Voltage	'ACT	4.5	5.0	5.5	v
V <sub>in</sub> , V <sub>out</sub>	DC Input Voltage, Output Voltage (Ref. to GND)		0	-	V <sub>CC</sub>	V
Input Rise and Fall Time (Note 1)	V <sub>CC</sub> @ 3.0 V	-	150	-		
	Input Rise and Fall Time (Note 1)  'AC Devices except Schmitt Inputs	V <sub>CC</sub> @ 4.5 V	-	40	-	ns/V
	, to 200,000 oxoopt oximit inputs	V <sub>CC</sub> @ 5.5 V	-	25	-	
	Input Rise and Fall Time (Note 2)	V <sub>CC</sub> @ 4.5 V	-	10	-	0.7
t <sub>r</sub> , t <sub>f</sub>	'ACT Devices except Schmitt Inputs	V <sub>CC</sub> @ 5.5 V	-	8.0	-	ns/V
T <sub>A</sub>	Operating Ambient Temperature Range		-40	25	85	°C
I <sub>OH</sub>	Output Current – High		-	-	-24	mA
I <sub>OL</sub>	Output Current – Low		-	-	24	mA

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

1. V<sub>in</sub> from 30% to 70% V<sub>CC</sub>; see individual Data Sheets for devices that differ from the typical input rise and fall times.

2. V<sub>in</sub> from 0.8 V to 2.0 V; see individual Data Sheets for devices that differ from the typical input rise and fall times.

#### **DC CHARACTERISTICS**

			74	AC	74AC		
		v <sub>cc</sub>	T <sub>A</sub> = +25°C		T <sub>A</sub> = -40°C to +85°C		
Symbol	Parameter	(V)	Тур	Guar	anteed Limits	Unit	Conditions
V <sub>IH</sub>	Minimum High Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	2.1 3.15 3.85	2.1 3.15 3.85	٧	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V
V <sub>IL</sub>	Maximum Low Level Input Voltage	3.0 4.5 5.5	1.5 2.25 2.75	0.9 1.35 1.65	0.9 1.35 1.65	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> - 0.1 V
V <sub>OH</sub>	Minimum High Level Output Voltage	3.0 4.5 5.5	2.99 4.49 5.49	2.9 4.4 5.4	2.9 4.4 5.4	V	I <sub>OUT</sub> = -50 μA
		3.0 4.5 5.5	- - -	2.56 3.86 4.86	2.46 3.76 4.76	V	$*V_{IN} = V_{IL} \text{ or } V_{IH}$ $-12 \text{ mA}$ $I_{OH}$ $-24 \text{ mA}$ $-24 \text{ mA}$
V <sub>OL</sub>	Maximum Low Level Output Voltage	3.0 4.5 5.5	0.002 0.001 0.001	0.1 0.1 0.1	0.1 0.1 0.1	V	I <sub>OUT</sub> = 50 μA
		3.0 4.5 5.5	- - -	0.36 0.36 0.36	0.44 0.44 0.44	V	$*V_{IN} = V_{IL} \text{ or } V_{IH}$ $12 \text{ mA}$ $I_{OL} \qquad 24 \text{ mA}$ $24 \text{ mA}$
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	-	±0.1	±1.0	μΑ	$V_I = V_{CC}$ , GND
I <sub>OLD</sub>	†Minimum Dynamic	5.5	-	-	75	mA	V <sub>OLD</sub> = 1.65 V Max
I <sub>OHD</sub>	Output Current	5.5	-	-	-75	mA	V <sub>OHD</sub> = 3.85 V Min
I <sub>CC</sub>	Maximum Quiescent Supply Current	5.5	-	4.0	40	μΑ	V <sub>IN</sub> = V <sub>CC</sub> or GND

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions. \*All outputs loaded; thresholds on input associated with output under test.

equal to the respective limit @ 5.5 V  $V_{CC}$ .

#### **AC CHARACTERISTICS**

		74AC		74AC				
		v <sub>cc</sub> *		Γ <sub>A</sub> = +25°C C <sub>L</sub> = 50 pF		T <sub>A</sub> = - to +8 C <sub>L</sub> = 8		
Symbol	Parameter	(v)	Min	Тур	Max	Min	Max	Unit
t <sub>PLH</sub>	Propagation Delay	3.3 5.0	1.5 1.5	5.0 4.0	7.5 6.0	1.0 1.0	8.0 6.5	ns
t <sub>PHL</sub>	Propagation Delay	3.3 5.0	1.5 1.5	5.0 4.5	7.5 6.5	1.0 1.0	8.0 7.0	ns

<sup>\*</sup>Voltage Range 3.3 V is 3.3 V  $\pm 0.3$  V. Voltage Range 5.0 V is 5.0 V ±0.5 V.

<sup>†</sup>Maximum test duration 2.0 ms, one output loaded at a time. NOTE:  $I_{\rm IN}$  and  $I_{\rm CC}$  @ 3.0 V are guaranteed to be less than or

#### **DC CHARACTERISTICS**

			74	CT	74ACT		
		v <sub>cc</sub>	T <sub>A</sub> = +25°C		T <sub>A</sub> = -40°C to +85°C		
Symbol	Parameter	(V)	Тур	Guar	anteed Limits	Unit	Conditions
V <sub>IH</sub>	Minimum High Level Input Voltage	4.5 5.5	1.5 1.5	2.0 2.0	2.0 2.0	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
V <sub>IL</sub>	Maximum Low Level Input Voltage	4.5 5.5	1.5 1.5	0.8	0.8 0.8	V	V <sub>OUT</sub> = 0.1 V or V <sub>CC</sub> – 0.1 V
V <sub>OH</sub>	Minimum High Level Output Voltage	4.5 5.5	4.49 5.49	4.4 5.4	4.4 5.4	V	I <sub>OUT</sub> = -50 μA
		4.5 5.5	- -	3.86 4.86	3.76 4.76	V	*V <sub>IN</sub> = V <sub>IL</sub> or V <sub>IH</sub> -24 mA I <sub>OH</sub> -24 mA
V <sub>OL</sub>	Maximum Low Level Output Voltage	4.5 5.5	0.001 0.001	0.1 0.1	0.1 0.1	V	I <sub>OUT</sub> = 50 μA
		4.5 5.5		0.36 0.36	0.44 0.44	٧	$*V_{IN} = V_{IL} \text{ or } V_{IH}$ $24 \text{ mA}$ $I_{OL} \qquad 24 \text{ mA}$
I <sub>IN</sub>	Maximum Input Leakage Current	5.5	_	±0.1	±1.0	μΑ	V <sub>I</sub> = V <sub>CC</sub> , GND
$\Delta I_{CCT}$	Additional Max. I <sub>CC</sub> /Input	5.5	0.6	-	1.5	mA	V <sub>I</sub> = V <sub>CC</sub> - 2.1 V
I <sub>OLD</sub>	†Minimum Dynamic		-	-	75	mA	V <sub>OLD</sub> = 1.65 V Max
I <sub>OHD</sub>	Output Current	5.5	_	-	-75	mA	V <sub>OHD</sub> = 3.85 V Min
I <sub>CC</sub>	Maximum Quiescent Supply Current	5.5	-	4.0	40	μА	V <sub>IN</sub> = V <sub>CC</sub> or GND

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

\*All outputs loaded; thresholds on input associated with output under test.

#### **AC CHARACTERISTICS**

				74ACT		74	CT	
		V <sub>CC</sub> *	7	- <sub>A</sub> = +25°C C <sub>L</sub> = 50 pF	) =	T <sub>A</sub> = - to +8 C <sub>L</sub> = 8		
Symbol	Parameter	(V)	Min	Тур	Max	Min	Max	Unit
t <sub>PLH</sub>	Propagation Delay	5.0	1.5	-	8.5	1.0	9.0	ns
t <sub>PHL</sub>	Propagation Delay	5.0	1.5	-	9.5	1.0	10	ns

<sup>\*</sup>Voltage Range 5.0 V is 5.0 V  $\pm 0.5$  V.

#### **CAPACITANCE**

Symbol	Parameter	Value Typ	Unit	Test Conditions
C <sub>IN</sub>	Input Capacitance	4.5	pF	V <sub>CC</sub> = 5.0 V
C <sub>PD</sub>	Power Dissipation Capacitance	30	pF	V <sub>CC</sub> = 5.0 V

<sup>†</sup>Maximum test duration 2.0 ms, one output loaded at a time.

#### **DEVICE ORDERING INFORMATION**

Device	Marking	Package	Shipping <sup>†</sup>
MC74AC02DG	AC02	SOIC-14 (Pb-Free)	55 Units / Rail
MC74AC02DR2G	AC02	SOIC-14 (Pb-Free)	2500 / Tape & Reel
MC74ACT02DG	ACT02	SOIC-14 (Pb-Free)	55 Units / Rail
MC74ACT02DR2G	ACT02	SOIC-14 (Pb-Free)	2500 / Tape & Reel
MC74AC02DTR2G	AC 02	TSSOP-14 (Pb-Free)	2500 / Tape & Reel
MC74ACT02DTR2G	ACT 02	TSSOP-14 (Pb-Free)	2500 / Tape & Reel

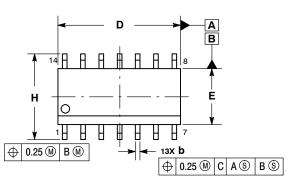
<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

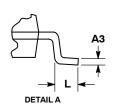


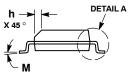
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SOIC-14 NB CASE 751A-03 ISSUE L

**DATE 03 FEB 2016** 





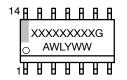




- NOTES:
  1. DIMENSIONING AND TOLERANCING PER
  - ASME Y14.5M, 1994.
    CONTROLLING DIMENSION: MILLIMETERS.
  - DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT
  - MAXIMUM MATERIAL CONDITION.
    DIMENSIONS D AND E DO NOT INCLUDE
    MOLD PROTRUSIONS.
- MAXIMUM MOLD PROTRUSION 0.15 PER SIDE

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	1.35	1.75	0.054	0.068	
A1	0.10	0.25	0.004	0.010	
АЗ	0.19	0.25	0.008	0.010	
b	0.35	0.49	0.014	0.019	
D	8.55	8.75	0.337	0.344	
Е	3.80	4.00	0.150	0.157	
е	1.27	BSC	0.050	BSC	
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.019	
L	0.40	1.25	0.016	0.049	
M	0 °	7°	0 °	7 °	

#### **GENERIC MARKING DIAGRAM\***



XXXXX = Specific Device Code Α = Assembly Location

WL = Wafer Lot Υ = Year WW = Work Week = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

#### SOI DERING FOOTBRINT\*

	SOLDERING	FOOTPRINT*	
1	6.5	50	14X - 1.18
			1.27
	——————————————————————————————————————		PITCH
14X A			
14X 0.58			

**DIMENSIONS: MILLIMETERS** 

#### **STYLES ON PAGE 2**

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<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### SOIC-14 CASE 751A-03 ISSUE L

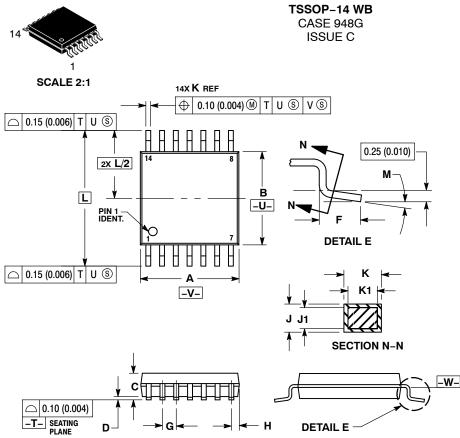
#### DATE 03 FEB 2016

STYLE 1: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. NO CONNECTION 5. ANODE/CATHODE 6. NO CONNECTION 7. ANODE/CATHODE 8. ANODE/CATHODE 9. ANODE/CATHODE 10. NO CONNECTION 11. ANODE/CATHODE 12. ANODE/CATHODE 13. NO CONNECTION 14. COMMON ANODE	STYLE 2: CANCELLED	STYLE 3: PIN 1. NO CONNECTION 2. ANODE 3. ANODE 4. NO CONNECTION 5. ANODE 6. NO CONNECTION 7. ANODE 8. ANODE 9. ANODE 10. NO CONNECTION 11. ANODE 12. ANODE 13. NO CONNECTION 14. COMMON CATHODE	STYLE 4: PIN 1. NO CONNECTION 2. CATHODE 3. CATHODE 4. NO CONNECTION 5. CATHODE 6. NO CONNECTION 7. CATHODE 8. CATHODE 9. CATHODE 10. NO CONNECTION 11. CATHODE 12. CATHODE 13. NO CONNECTION 14. COMMON ANODE
STYLE 5: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. ANODE/CATHODE 5. ANODE/CATHODE 6. NO CONNECTION 7. COMMON ANODE 8. COMMON CATHODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. ANODE/CATHODE 12. ANODE/CATHODE 13. NO CONNECTION 14. COMMON ANODE	STYLE 6: PIN 1. CATHODE 2. CATHODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE 7. CATHODE 8. ANODE 9. ANODE 10. ANODE 11. ANODE 12. ANODE 13. ANODE 14. ANODE	STYLE 7: PIN 1. ANODE/CATHODE 2. COMMON ANODE 3. COMMON CATHODE 4. ANODE/CATHODE 5. ANODE/CATHODE 6. ANODE/CATHODE 7. ANODE/CATHODE 8. ANODE/CATHODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. COMMON CATHODE 12. COMMON ANODE 13. ANODE/CATHODE 14. ANODE/CATHODE	STYLE 8: PIN 1. COMMON CATHODE 2. ANODE/CATHODE 3. ANODE/CATHODE 4. NO CONNECTION 5. ANODE/CATHODE 6. ANODE/CATHODE 7. COMMON ANODE 8. COMMON ANODE 9. ANODE/CATHODE 10. ANODE/CATHODE 11. NO CONNECTION 12. ANODE/CATHODE 13. ANODE/CATHODE 14. COMMON CATHODE

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**SOLDERING FOOTPRINT** 

7.06

14X

1.26

**DATE 17 FEB 2016** 

- NOTES.

  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

  2. CONTROLLING DIMENSION: MILLIMETER.

  3. DIMENSION A DOES NOT INCLUDE MOLD
- FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
  DIMENSION B DOES NOT INCLUDE
- INTERLEAD FLASH OR PROTRUSION.
  INTERLEAD FLASH OR PROTRUSION SHALL
- INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

  5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL CONDITION.

  6. TERMINAL NUMBERS ARE SHOWN FOR DEFERENCE ONLY
- REFERENCE ONLY.
  DIMENSION A AND B ARE TO BE
- DETERMINED AT DATUM PLANE -W-.

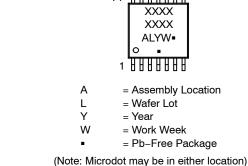
	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65 BSC		0.026 BSC	
Н	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
K	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40 BSC		0.252 BSC	
М	0°	8 °	0 °	8 °

#### **GENERIC MARKING DIAGRAM\***

XXXX XXXX

ALYW= O 1 1000000

= Assembly Location = Wafer Lot



= Work Week = Pb-Free Package

- Year

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	TSSOP-14 WB		PAGE 1 OF 1	

DIMENSIONS: MILLIMETERS

0.65

**PITCH** 

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14X

0.36

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